

Description Continued

The power amplifier output stage allows the UCC5614 to source full termination current and sink active negation current when all termination lines are actively negated.

The UCC5614 is pin for pin compatible with Unitrode's other 9 line SCSI terminators, allowing lower capacitance and lower voltage upgrades to existing systems. The UCC5614, as with all Unitrode terminators, is completely hot pluggable and appears as high impedance at the terminating channels with $V_{TRMPWR} = 0V$ or open.

Internal circuit trimming is utilized, first to trim the 110 ohm termination impedance to a 7% tolerance, and then

most importantly, to trim the output current to a 4% tolerance, as close to the max SCSI-3 spec as possible, which maximizes noise margin in fast SCSI operation.

Other features include thermal shutdown and current limit.

This device is offered in low thermal resistance versions of the industry standard 16 pin narrow body SOIC, 16 pin ZIP (Zig-Zag In Line package), 24 pin TSSOP and 28 pin PLCC.

ABSOLUTE MAXIMUM RATINGS

Tempwr Voltage +7V
Signal Line Voltage 0V to +7V
Regulator Output Current 0.6A
Storage Temperature -65°C to +150°C
Operating Temperature -55°C to +150°C
Lead Temperature (Soldering, 10 Sec.) +300°C

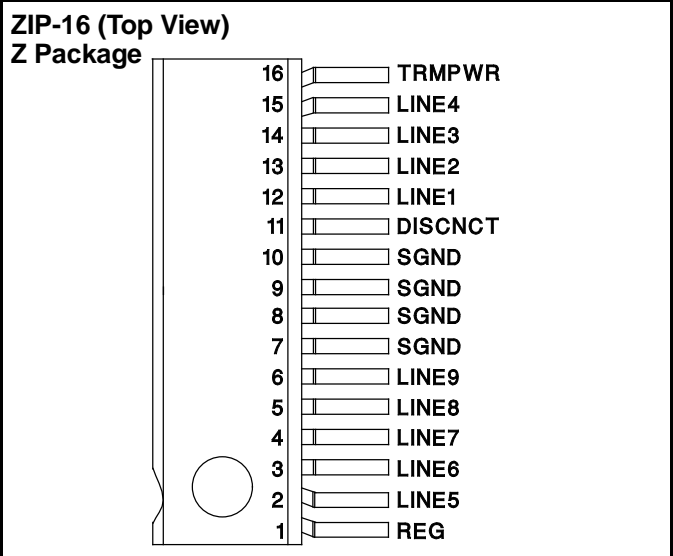
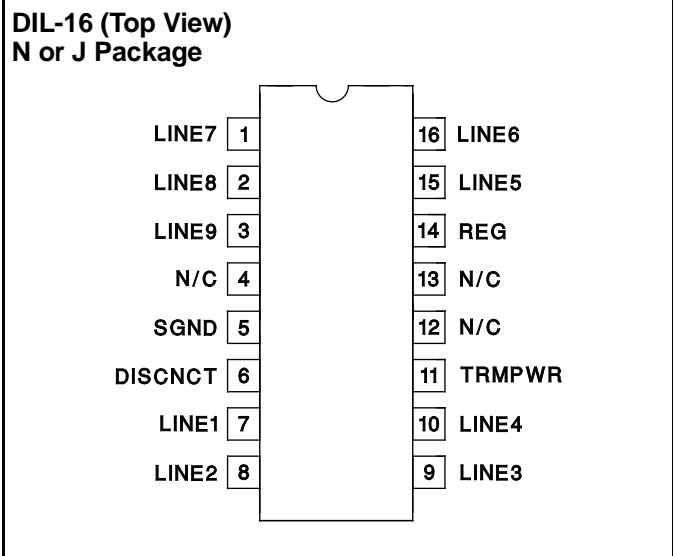
Unless otherwise specified all voltages are with respect to Ground. Currents are positive into, negative out of the specified terminal.

Consult Packaging Section of Unitrode Integrated Circuits databook for thermal limitations and considerations of packages.

RECOMMENDED OPERATING CONDITIONS

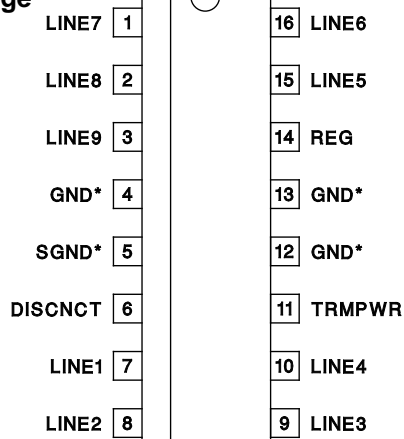
Tempwr Voltage 2.7V to 5.25V
Signal Line Voltage 0V to +5V
Disconnect Input Voltage 0V to Tempwr

CONNECTION DIAGRAMS



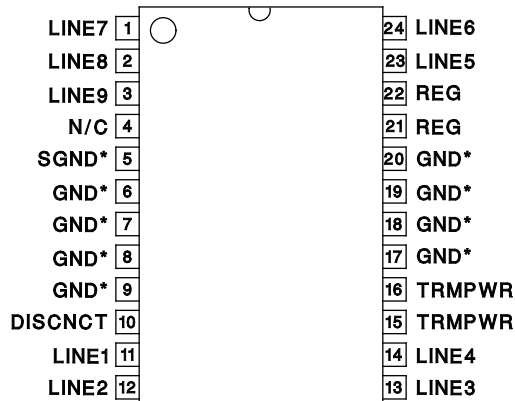
Note: Drawings are not to scale.

CONNECTION DIAGRAMS (cont.)

SOIC-16 (Top View)
DP Package

* DP package pin 5 serves as signal ground; pins 4, 12, 13 serve as heatsink/ground.

Note: Drawings are not to scale.

TSSOP-24 (Top View)
PWP Package

* PWP package pin 5 serves as signal ground; pins 6, 7, 8, 9, 17, 18, 19, and 20 serve as heatsink/ground.

ELECTRICAL CHARACTERISTICS Unless otherwise stated, these specifications apply for $T_A = 0^\circ\text{C}$ to 70°C .
TRMPWR = 3.3V, DISCNCT = 0V, RDISCNCT = 0 ohms. $T_A = T_J$.

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNITS
Supply Current Section					
Termpwr Supply Current	All termination lines = Open		1	2	mA
	All termination lines = 0.2V		210	218	mA
Power Down Mode	DISCNCT = Termpwr		0.5	5	μA
Output Section (110 ohms - Terminator Lines)					
Terminator Impedance		102.3	110	117.7	Ohms
Output High Voltage	(Note 1)	2.5	2.7	3.0	V
Max Output Current	VLINE = 0.2V $T_J = 25^\circ\text{C}$	-22.1	-23	-24	mA
	VLINE = 0.2V	-21	-23	-24	mA
	VLINE = 0.2V, TRMPWR = 3V $T_J = 25^\circ\text{C}$ (Note 1)	-20.2	-23	-24	mA
	VLINE = 0.2V, TRMPWR = 3V (Note 1)	-19	-23	-24	mA
	VLINE = 0.5V			-22.4	mA
Output Leakage	DISCNCT = 2.4V, TRMPWR = 0V to 5.25V		10	400	nA
Output Capacitance	DISCNCT = 2.4V (Note 2) (DP Package)		1.8	2.5	pF
Output Section (2.5k ohms - Terminator Lines) (RDISCNCT = 80k ohms)					
Terminator Impedance		2	2.5	3	k Ω
Output High Voltage	TRMPWR = 3V (Note 1)	2.5	2.7	3.0	V
Max Output Current	VLINE = 0.2V	-0.7	-1	-1.4	mA
	VLINE = 0.2V, TRMPWR = 3V (Note 1)	-0.6	-1	-1.5	mA
Output Leakage	DISCNCT = 2.4V, TRMPWR = 0 to 5.25V		10	400	nA
Output Capacitance	DISCNCT = 2.4V (Note 2) (DP Package)		1.8	2.5	pF
Regulator Section					
Regulator Output Voltage	5.25V > TRMPWR > 3V	2.5	2.7	3.0	V
Drop Out Voltage	All Termination Lines = 0.2V		0.1	0.2	V
Short Circuit Current	VREG = 0V	-200	-400	-800	mA

ELECTRICAL CHARACTERISTICS (cont.) Unless otherwise stated, these specifications apply for $T_A = 0^\circ\text{C}$ to 70°C .
 $\text{TRMPWR} = 3.3\text{V}$, $\text{DISCNCNT} = 0\text{V}$, $\text{RDISCNCNT} = 0\text{ ohms}$. $T_A = T_J$.

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNITS
Regulator Section (cont.)					
Sinking Current Capability	$V_{\text{REG}} = 3\text{V}$	200	400	800	mA
Thermal Shutdown	(Note 2)		170		$^\circ\text{C}$
Thermal Shutdown Hysteresis	(Note 2)		10		$^\circ\text{C}$
Disconnect Section					
Disconnect Threshold	$\text{RDISCNCNT} = 0 \text{ \& } 80\text{k}$	0.8	1.5	2.0	V
Input Current	$\text{DISCNCNT} = 0\text{V}$		30	50	μA

Note 1: Measuring each termination line while other 8 are low (0.2V).

Note 2: Guaranteed by design. Not 100% tested in production.

APPLICATION INFORMATION

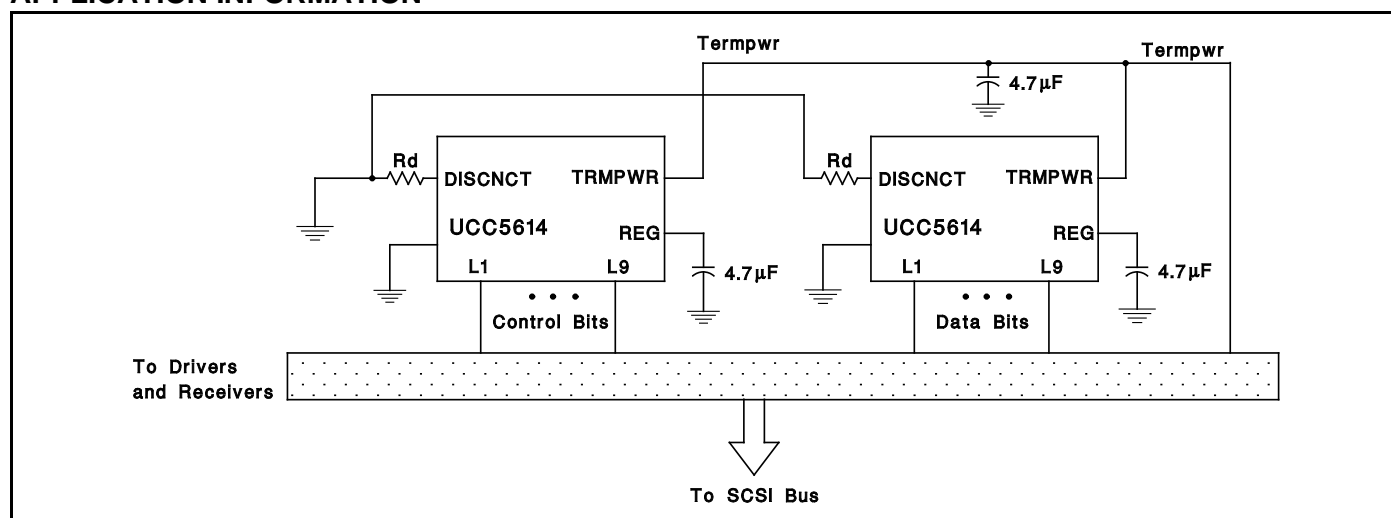


Figure 1: Typical SCSI Bus Configurations Utilizing 2 UCC5614 Devices

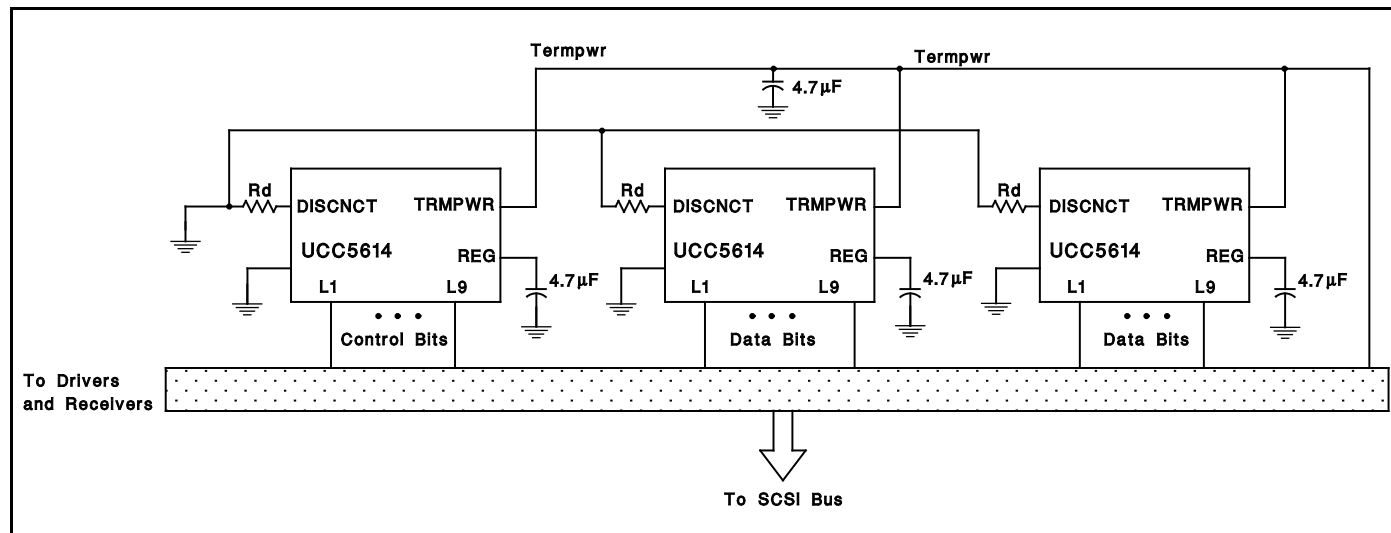


Figure 2: Typical Wide SCSI Bus Configurations Utilizing 3 UCC5614 Devices.

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